

Complementary MOSFET

ELM14603AA-N

■ General Description

ELM14603AA-N uses advanced trench technology to provide excellent Rds(on) and low gate charge.

■ Features

N-channel	P-channel
• Vds=30V	Vds=-30V
• Id=4.7A(Vgs=10V)	Id=-5.8A(Vgs=-10V)
• Rds(on) < 55mΩ (Vgs=10V)	Rds(on) < 38mΩ (Vgs=-10V)
• Rds(on) < 70mΩ (Vgs=4.5V)	Rds(on) < 63mΩ (Vgs=-4.5V)
• Rds(on) < 110mΩ (Vgs=2.5V)	

■ Maximum Absolute Ratings

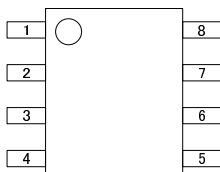
Parameter	Symbol	N-ch (Max.)	P-ch (Max.)	Unit	Note
Drain-source voltage	Vds	30	-30	V	
Gate-source voltage	Vgs	±12	±20	V	
Continuous drain current	Id	4.7	-5.8	A	1
		4.0	-4.9		
Pulsed drain current	Idm	30	-40	A	2
Power dissipation	Pd	2.00	2.00	W	
		1.44	1.44		
Junction and storage temperature range	Tj,Tstg	-55 to 150	-55 to 150	°C	

■ Thermal Characteristics

Parameter	Symbol	Device	Typ.	Max.	Unit	Note
Maximum junction-to-ambient	Rθja	N-ch	52.0	62.5	°C/W	1
Maximum junction-to-ambient			78.0	110.0	°C/W	
Maximum junction-to-lead			48.0	50.0	°C/W	
Maximum junction-to-ambient	Rθja	P-ch	50.0	62.5	°C/W	1
Maximum junction-to-ambient			73.0	110.0	°C/W	
Maximum junction-to-lead			31.0	35.0	°C/W	

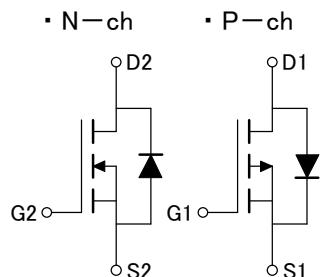
■ Pin Configuration

SOP-8 (TOP VIEW)



Pin No.	Pin name
1	SOURCE2
2	GATE2
3	SOURCE1
4	GATE1
5	DRAIN1
6	DRAIN1
7	DRAIN2
8	DRAIN2

■ Circuit



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■ Electrical Characteristics (N-ch)

T_a=25°C

Parameter	Symbol	Conditions		Min.	Typ.	Max.	Unit	
STATIC PARAMETERS								
Drain-source breakdown voltage	BV _{dss}	Id=250 μA, V _{gs} =0V		30			V	
Zero gate voltage drain current	Id _{ss}	V _{ds} =24V V _{gs} =0V	T _j =55°C			1	μA	
						5		
Gate-body leakage current	I _{gss}	V _{ds} =0V, V _{gs} =±12V				100	nA	
Gate threshold voltage	V _{gs(th)}	V _{ds} =V _{gs} , Id=250 μA		0.6	1.0	1.4	V	
On state drain current	Id(on)	V _{gs} =4.5V, V _{ds} =5V		10			A	
Static drain-source on-resistance	R _{ds(on)}	V _{gs} =10V Id=4A	T _j =125°C		45	55	mΩ	
		V _{gs} =4.5V, Id=3A			55	70		
		V _{gs} =2.5V, Id=2A			83	110		
Forward transconductance	G _f	V _{ds} =5V, Id=4A			8		S	
Diode forward voltage	V _{sd}	I _s =1A, V _{gs} =0V			0.8	1.0	V	
Max.body-diode continuous current	I _s					2.5	A	
DYNAMIC PARAMETERS								
Input capacitance	C _{iss}	V _{gs} =0V, V _{ds} =15V, f=1MHz			390.0		pF	
Output capacitance	C _{oss}				54.5		pF	
Reverse transfer capacitance	C _{rss}				41.0		pF	
Gate resistance	R _g	V _{gs} =0V, V _{ds} =0V, f=1MHz			3		Ω	
SWITCHING PARAMETERS								
Total gate charge	Q _g	V _{gs} =4.5V, V _{ds} =15V, Id=4A			0.60		nC	
Gate-source charge	Q _{gs}				1.38		nC	
Gate-drain charge	Q _{gd}				4.34		nC	
Turn-on delay time	td(on)	V _{gs} =10V, V _{ds} =15V RL=3.75 Ω, R _{gen} =6 Ω			3.3		ns	
Turn-on rise time	tr				1.0		ns	
Turn-off delay time	td(off)				21.7		ns	
Turn-off fall time	tf				2.1		ns	
Body-diode reverse recovery time	trr				12.0		ns	
Body-diode reverse recovery charge	Qrr	If=4A, dl/dt=100A/μs			6.3		nC	

NOTE :

1. The value of R_{θja} is measured with the device mounted on 1in² FR-4 board of 2oz. Copper, in still air environment with T_a=25°C. The value in any given applications depends on the user's specific board design, The current rating is based on the t≤10s thermal resistance rating.
2. Repetitive rating, pulse width limited by junction temperature.
3. The R_{θja} is the sum of the thermal impedance from junction to lead R_{θjl} and lead to ambient.
4. The static characteristics in Figures 1 to 6 are obtained using 80μs pulses, duty cycle 0.5%max.
5. These tests are performed with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_a=25°C. The SOA curve provides a single pulse rating.

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■ Typical Electrical and Thermal Characteristics (N-ch)

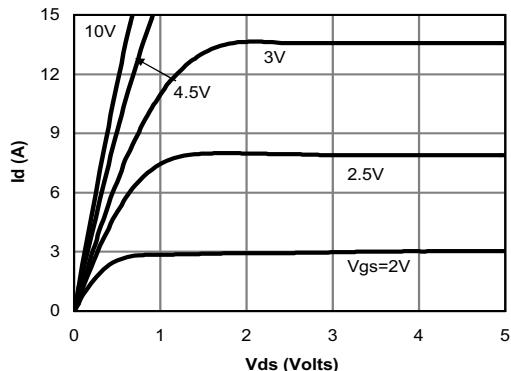


Fig 1: On-Region Characteristics

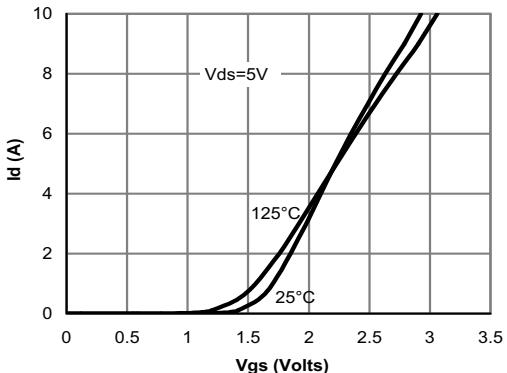


Figure 2: Transfer Characteristics

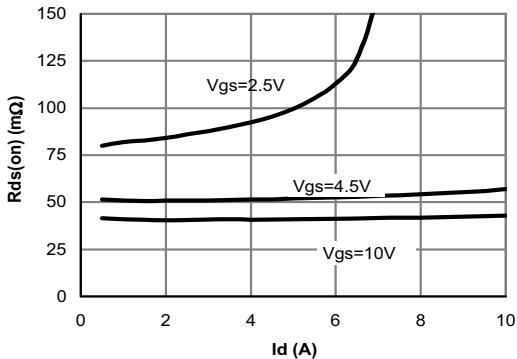


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

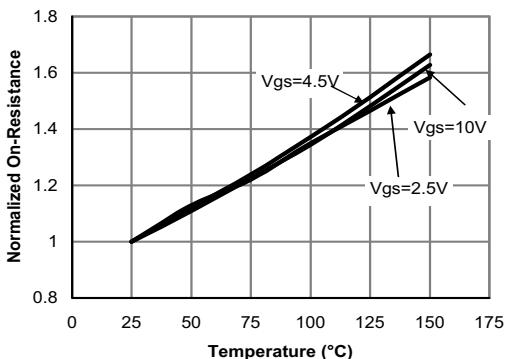


Figure 4: On-Resistance vs. Junction Temperature

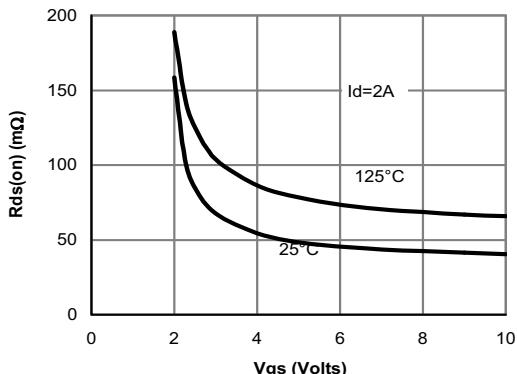


Figure 5: On-Resistance vs. Gate-Source Voltage

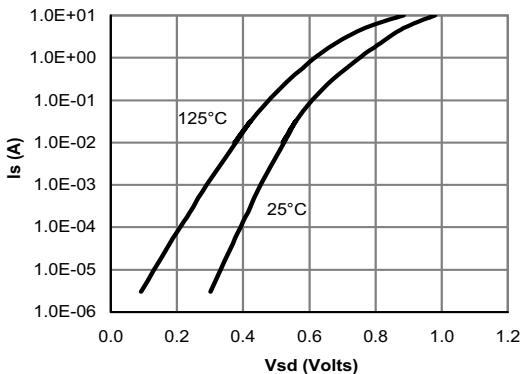


Figure 6: Body-Diode Characteristics

Complementary MOSFET

ELM14603AA-N

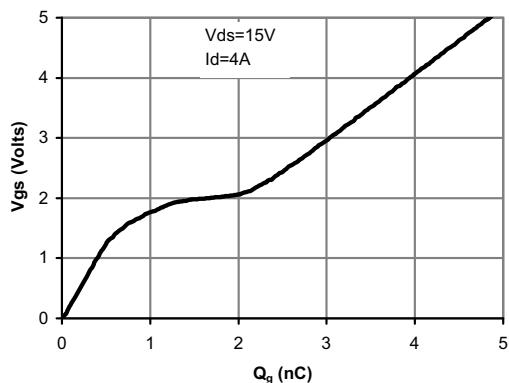


Figure 7: Gate-Charge Characteristics

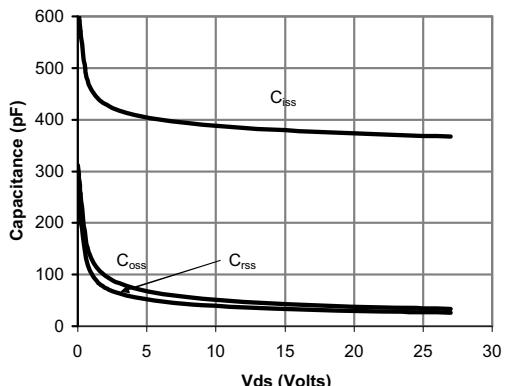


Figure 8: Capacitance Characteristics

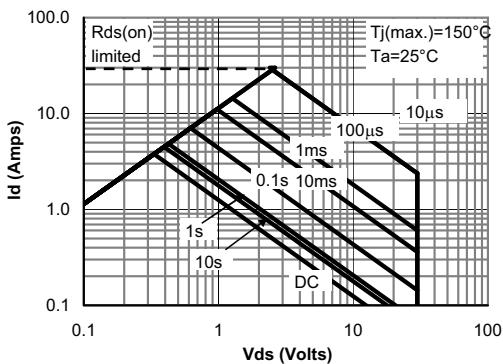


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

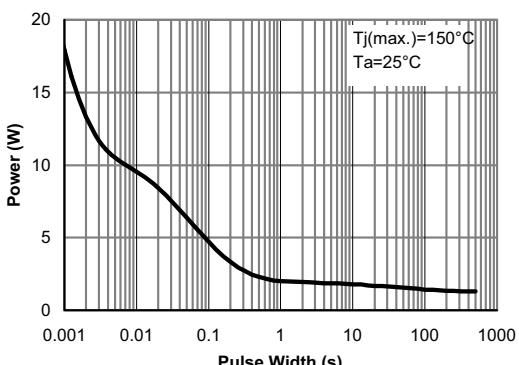


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

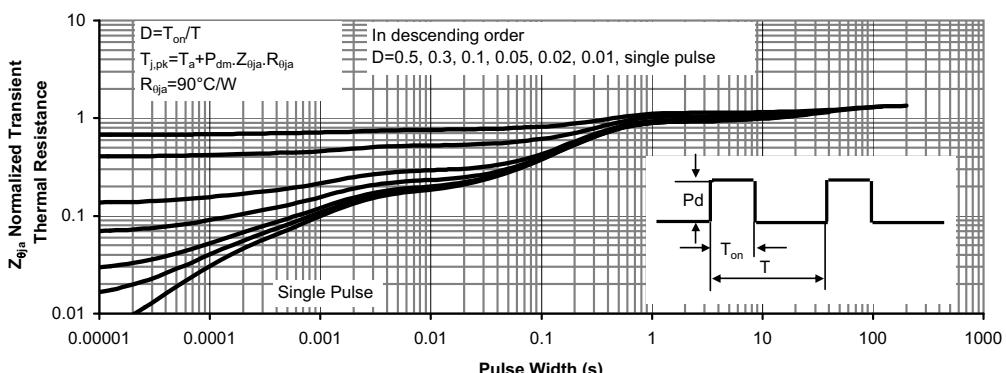


Figure 11: Normalized Maximum Transient Thermal Impedance

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■ Electrical Characteristics (P-ch)

T_a=25°C

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
STATIC PARAMETERS						
Drain-source breakdown voltage	BVdss	Id=-250 μA, Vgs=0V	-30			V
Zero gate voltage drain current	Idss	Vds=-24V			-1	μ A
		Vgs=0V	Tj=55°C		-5	
Gate-body leakage current	Igss	Vds=0V, Vgs=±20V			±100	nA
Gate threshold voltage	Vgs(th)	Vds=Vgs, Id=-250 μA	-1.2	-1.8	-2.2	V
On state drain current	Id(on)	Vgs=-10V, Vds=-5V	-40			A
Static drain-source on-resistance	Rds(on)	Vgs=-10V		29	38	m Ω
		Id=-5A	Tj=125°C	40		
		Vgs=-4.5V, Id=-5A		39	63	m Ω
Forward transconductance	Gfs	Vds=-5V, Id=-10A				S
Diode forward voltage	Vsd	Is=-1A, Vgs=0V		-0.75	-1.00	V
Max. body-diode continuous current	Is				-4.2	A
DYNAMIC PARAMETERS						
Input capacitance	Ciss	Vgs=0V, Vds=-15V, f=1MHz		920		pF
Output capacitance	Coss			190		pF
Reverse transfer capacitance	Crss			122		pF
Gate resistance	Rg	Vgs=0V, Vds=0V, f=1MHz		3.6		Ω
SWITCHING PARAMETERS						
Total gate charge	Qg	Vgs=-10V, Vds=-15V Id=-7.5A		2.4		nC
Gate-source charge	Qgs			4.5		nC
Gate-drain charge	Qgd			9.3		nC
Turn-on delay time	td(on)	Vgs=-10V, Vds=-15V RL=2 Ω, Rgen=3 Ω		7.6		ns
Turn-on rise time	tr			5.2		ns
Turn-off delay time	td(off)			21.6		ns
Turn-off fall time	tf			8.0		ns
Body diode reverse recovery time	trr		If=-7.5A, dl/dt=100A/μs	20.0		ns
Body diode reverse recovery charge	Qrr		If=-7.5A, dl/dt=100A/μs	8.8		nC

NOTE :

1. The value of R_{θja} is measured with the device mounted on 1in² FR-4 board of 2oz. Copper, in still air environment with T_a=25°C. The value in any given applications depends on the user's specific board design, The current rating is based on the t≤10s thermal resistance rating.
2. Repetitive rating, pulse width limited by junction temperature.
3. The R_{θja} is the sum of the thermal impedance from junction to lead R_{θjl} and lead to ambient.
4. The static characteristics in Figures 1 to 6 are obtained using 80μs pulses, duty cycle 0.5%max.
5. These tests are performed with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with T_a=25°C. The SOA curve provides a single pulse rating.

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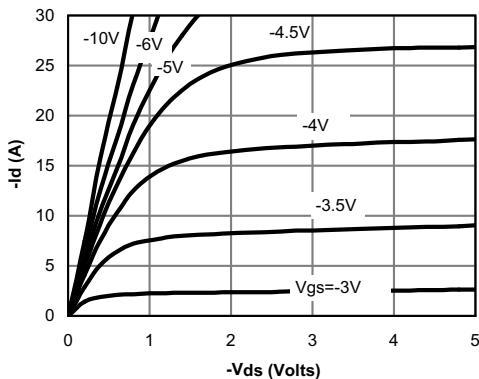


Fig 1: On-Region Characteristics

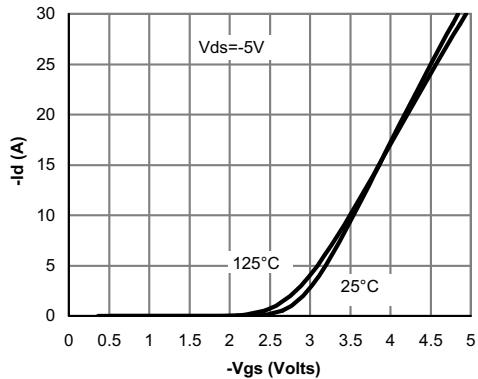


Figure 2: Transfer Characteristics

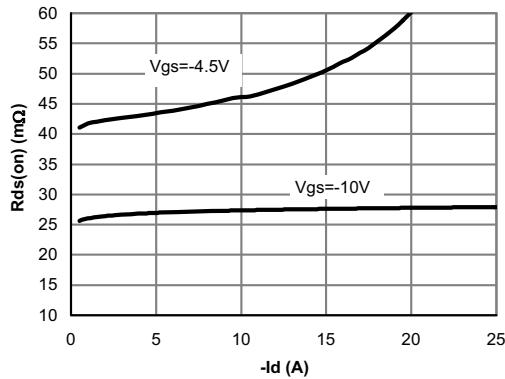


Figure 3: On-Resistance vs. Drain Current and Gate Voltage

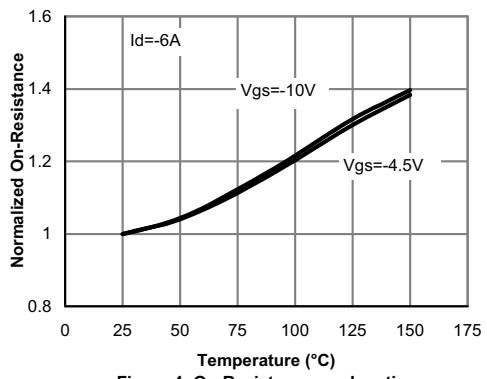


Figure 4: On-Resistance vs. Junction Temperature

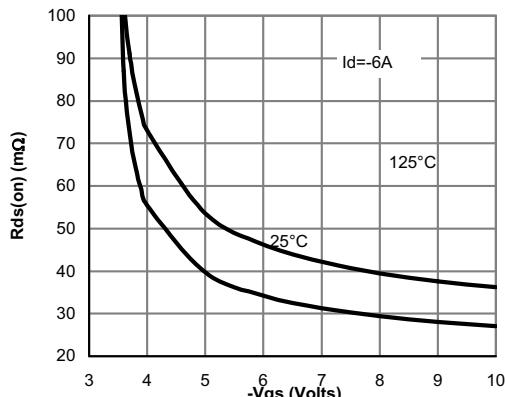


Figure 5: On-Resistance vs. Gate-Source Voltage

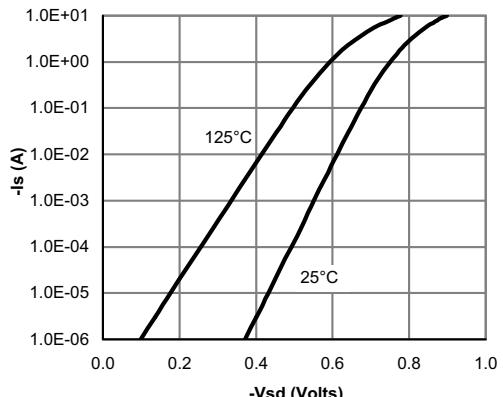


Figure 6: Body-Diode Characteristics

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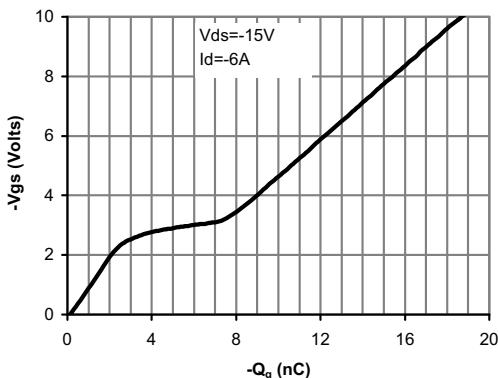


Figure 7: Gate-Charge Characteristics

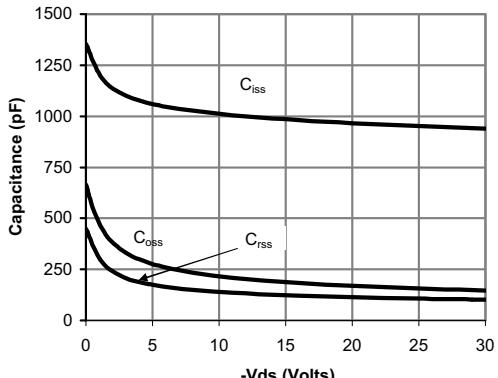


Figure 8: Capacitance Characteristics

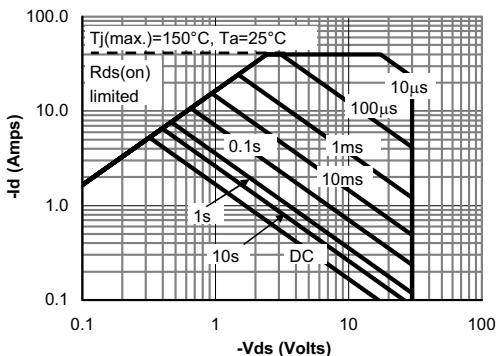


Figure 9: Maximum Forward Biased Safe Operating Area (Note E)

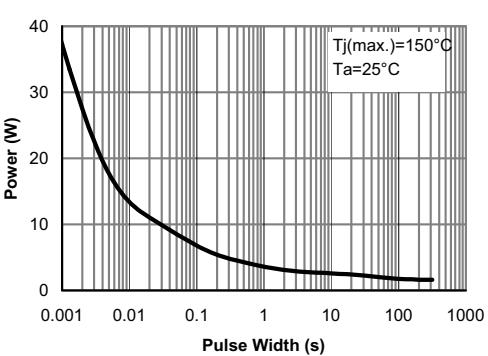


Figure 10: Single Pulse Power Rating Junction-to-Ambient (Note E)

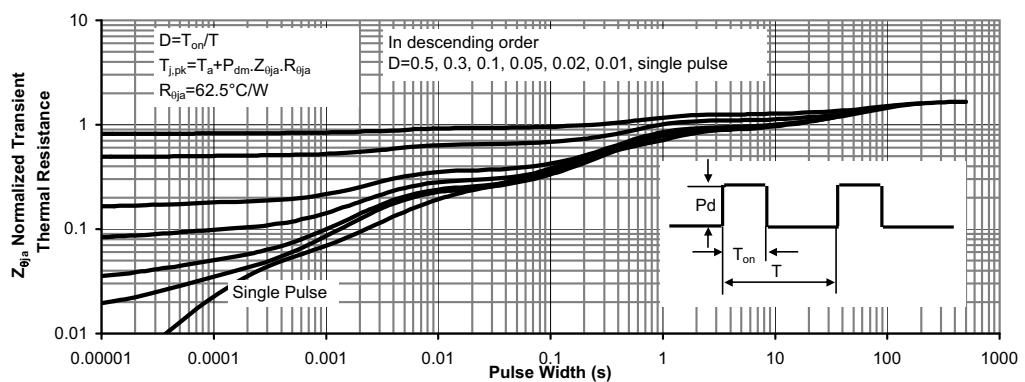


Figure 11: Normalized Maximum Transient Thermal Impedance